

GP 2813

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



#6/A
Hines
12-8-00

In re application of

THEODORE W. HOUSTON

Serial No. 09/346,436 (TI-21004)

Filed July 1, 1999

For: BONDED SOI WITH BURIED INTERCONNECT TO HANDLE OR DEVICE WAFER

Art Unit 2813

Examiner E. Kielin

Commissioner for Patents
Washington, D. C. 20231

Sir:

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AMENDMENT UNDER 37 C.F.R. 1.111

In response to the Office action dated August 8, 2000, please amend the above-identified application as follows:

In the specification:

Page 6, line 18 after the period (.) add "The interconnects 7 and 11 are connected to bond regions 19."

In the claims:

Amend claim 1 as follows:

1. (Amended) A method of fabricating an SOI structure which comprises the steps of:

(a) providing a substrate having at least one of active or passive elements on a surface thereof and a device wafer having at least one of active or passive elements on a surface thereof;

A2
Sub 7
B1